## SN74LV86A-Q1 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATE

SCLS534C - AUGUST 2003 - REVISED APRIL 2008

Qualified for Automotive Applications

- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- 2-V to 5.5-V V<sub>CC</sub> Operation
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
   >2.3 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Support Mixed-Mode Voltage Operation on All Ports

#### **PW PACKAGE** (TOP VIEW) 14 🛮 V<sub>CC</sub> 1A [ 1B **∏** 2 13 AB 1Y **∏** 3 12**∏** 4A 11 🛮 4Y 2A | 2В [ 10**∏** 3B 2Y 🛮 9 🛮 3A 8 🛚 3Y GND L

### description/ordering information

The SN74LV86A is a quadruple 2-input exclusive-OR gate designed for 2-V to 5.5-V V<sub>CC</sub> operation.

This device contains four independent 2-input exclusive-OR gates. It performs the Boolean function  $Y = A \oplus B$  or  $Y = \overline{AB} + A\overline{B}$  in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

#### ORDERING INFORMATION<sup>†</sup>

TA	PACK	\GE <sup>‡</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	TSSOP - PW	Tape and reel	SN74LV86ATPWRQ1	LV86AT

<sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

## FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Y
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L

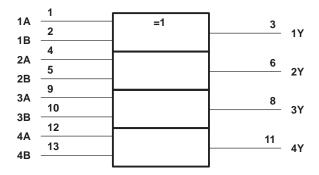


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>‡</sup> Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

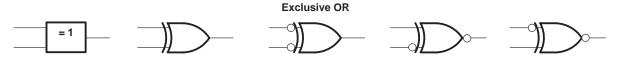
#### logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

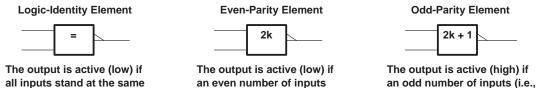
#### exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These are five equivalent exclusive-OR symbols valid for an 'LV86A gate in positive logic; negation can be shown at any two ports.

only 1 of the 2) are active.



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

(i.e., 0 or 2) are active.

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V <sub>O</sub> (see Note 1)	0.5 V to 7 V
Output voltage range, VO (see Notes 1 and 2)	$\dots$ -0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, $I_{ K }(V_{ C } < 0)$	–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3)	113°C/W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. This value is limited to 5.5 V maximum.

logic level (i.e., A = B).

3. The package thermal impedance is calculated in accordance with JESD 51-7.



### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
VCC	Supply voltage		2	5.5	V	
		V <sub>CC</sub> = 2 V	1.5			
V	High level innerteeling	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V <sub>CC</sub> ×0.7		V	
$V_{IH}$	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	V <sub>CC</sub> ×0.7		V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	V <sub>CC</sub> ×0.7			
		V <sub>CC</sub> = 2 V		0.5		
V	Lavy laval innyt valtage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V	
$V_{IL}$	Low-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		$V_{CC} \times 0.3$	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$V_{CC} \times 0.3$		
VI	Input voltage		0	5.5	V	
VO	Output voltage		0	Vcc	V	
		V <sub>CC</sub> = 2 V		-50	μΑ	
	High-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		
ЮН		V <sub>CC</sub> = 3 V to 3.6 V		-6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		
		V <sub>CC</sub> = 2 V		50	μΑ	
	Level level entered entered	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		
loL	Low-level output current	V <sub>CC</sub> = 3 V to 3.6 V		6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	0	200		
Δt/Δν	Input transition rise or fall rate	V <sub>CC</sub> = 3 V to 3.6 V	0	100	ns/V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0	20		
TA	Operating free-air temperature		-40	105	°C	

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		VCC	MIN	TYP	MAX	UNIT
	I <sub>OH</sub> = -50 μA	2 V to 5.5 V	V <sub>CC</sub> -0.1				
.,	I <sub>OH</sub> = -2 mA		2.3 V	2			.,
VOH	I <sub>OH</sub> = -6 mA		3 V	2.48			V
	I <sub>OH</sub> = −12 mA		4.5 V	3.8			
	I <sub>OL</sub> = 50 μA		2 V to 5.5 V			0.1	
	I <sub>OL</sub> = 2 mA		2.3 V			0.4	V
VOL	I <sub>OL</sub> = 6 mA		3 V			0.44	V
	I <sub>OL</sub> = 12 mA		4.5 V			0.55	
IĮ	V <sub>I</sub> = 5.5 V or GND		0 to 5.5 V			±1	μΑ
Icc	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V			20	μΑ
loff	$V_I$ or $V_O = 0$ to 5.5 $V$		0			5	μΑ
Ci	$V_I = V_{CC}$ or GND		3.3 V		1.4		pF

### SN74LV86A-Q1 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATE

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## switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	T,	չ = 25°C	;		MAY	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
t <sub>pd</sub>	A or B	Υ	C <sub>L</sub> = 50 pF		10.5	22.6	1	26.5	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	<b>Վ = 25°</b> C	;	MINI	MAV	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
t <sub>pd</sub>	A or B	Υ	C <sub>L</sub> = 50 pF		7.4	14.5	1	16.5	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	<b>Վ = 25°</b> C	;	MAINI	MAY	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
t <sub>pd</sub>	A or B	Υ	C <sub>L</sub> = 50 pF		5.3	8.8	1	10	ns

## noise characteristics, $V_{CC}$ = 3.3 V, $C_L$ = 50 pF, $T_A$ = 25°C (see Note 5)

	PARAMETER	MIN	TYP	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic VOL		0.2	0.8	V
VOL(V)	Quiet output, minimum dynamic VOL		-0.1	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		3.1		V
V <sub>IH</sub> (D)	High-level dynamic input voltage	2.31			V
V <sub>IL(D)</sub>	Low-level dynamic input voltage			0.99	V

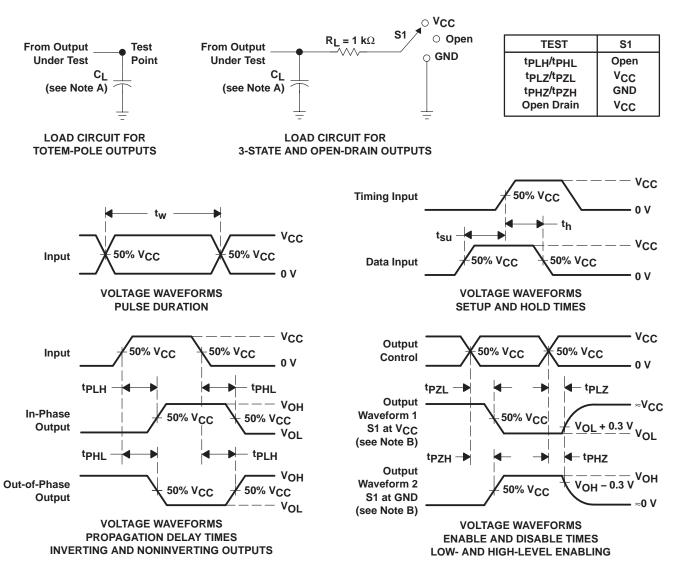
NOTE 5: Characteristics are for surface-mount packages only.

#### operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	VCC	TYP	UNIT
<u> </u>	Davies dissination conseitance	C. 50 = 5 40 MH=	3.3 V	8.4	٠.
Cpd	Power dissipation capacitance	$C_L = 50 \text{ pF},  f = 10 \text{ MHz}$	5 V	8.8	pF



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq 3$  ns,  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzi and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





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#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
SN74LV86ATPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV86AT	Samples
SN74LV86ATPWRQ1	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 105	LV86AT	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF SN74LV86A-Q1:

Catalog: SN74LV86A

<sup>(4)</sup> Only one of markings shown within the brackets will appear on the physical device.





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● Enhanced Product: SN74LV86A-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

## **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV86ATPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV86ATPWRG4Q1	TSSOP	PW	14	2000	367.0	367.0	35.0

PW (R-PDSO-G14)

### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
  - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



## PW (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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